MOSEL VITELIC   V62C18161024
### 1.8 VOLT 128K x 16 STATIC RAM

ADVANCED

Features

■ High-speed: 90, 120 ns
■ Ultra low DC operating current of 4mA (max.)
  – CMOS Standby: 1 μA
■ Fully static operation
■ All inputs and outputs directly TTL compatible
■ Three state outputs
■ Ultra low data retention current (V_{CC} = 1.6V)
■ Extended Operating Voltage: 1.8V – 2.2V
■ Packages
  – 44-pin TSOP

Description

The V62C18161024 is a 2,097,152-bit static random-access memory organized as 131,072 words by 16 bits. It is built with MOSEL VITELIC's high performance CMOS process. Inputs and three-state outputs are TTL compatible and allow for direct interfacing with common system bus structures.

Functional Block Diagram

18161024-01
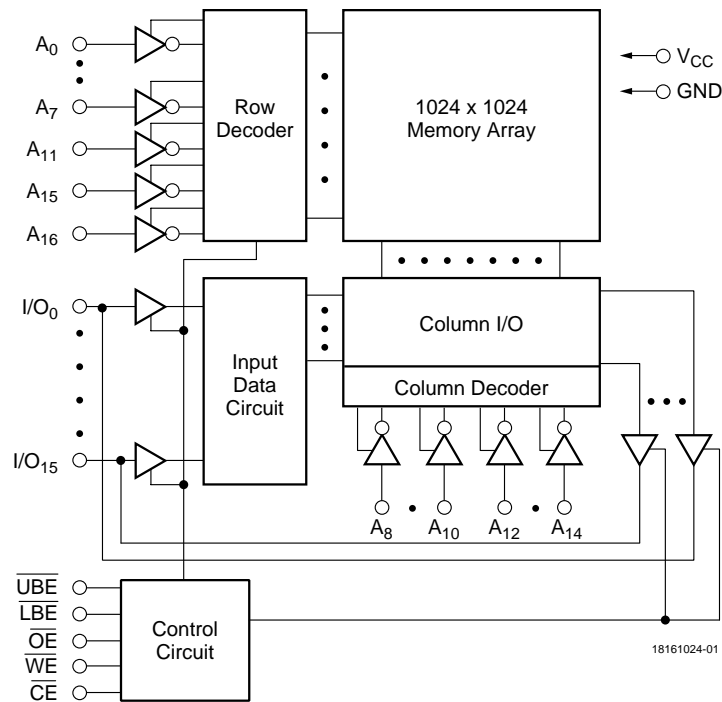
Device Usage Chart

Operating Temperature Range	Package Outline	Access Time (ns)		Power		Temperature Mark
	T	90	120	L	LL	
0°C to 70 °C	•	•	•	•	•	Blank
−40°C to +85°C	•	•			•	I

Pin Descriptions

A_0–A_{16} Address Inputs
These 16 address inputs select one of the 128K x 16 bit segments in the RAM.

$\overline{CE}$, CE2*   Chip Enable Inputs
$\overline{CE}$ is active LOW. CE2 is active High. It must be active to read from or write to the device. If chip enable is not active, the device is deselected and is in a standby power mode. The I/O pins will be in the high-impedance state when deselected.

$\overline{OE}$ Output Enable Input
The output enable input is active LOW. When $\overline{OE}$ is Low with $\overline{CE}$ Low and $\overline{WE}$ High, data will be presented on the I/O pins. The I/O pins will be in the high impedance state when $\overline{OE}$ is High.

$\overline{UBE}$, $\overline{LEB}$ Byte Enable
Active low inputs. These inputs are used to enable the upper or lower data byte.

$\overline{WE}$ Write Enable Input
The write enable input is active LOW and controls read and write operations. With the chip enabled, when $\overline{WE}$ is HIGH and $\overline{OE}$ is LOW, output data will be present at the I/O pins; when $\overline{WE}$ is LOW and $\overline{OE}$ is HIGH, the data present on the I/O pins will be written into the selected memory locations.

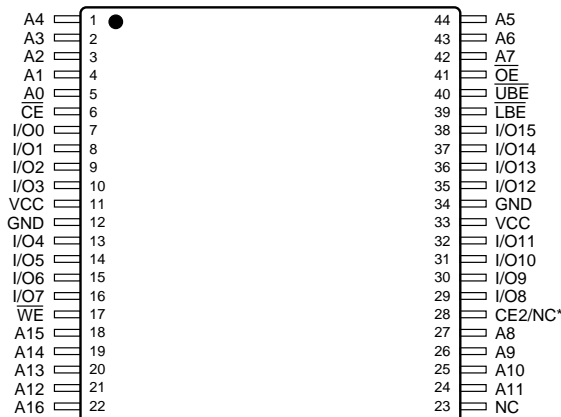**I/O_0–I/O_{15} Data Input and Data Output Ports**
These 16 bidirectional ports are used to read data from and write data into the RAM.

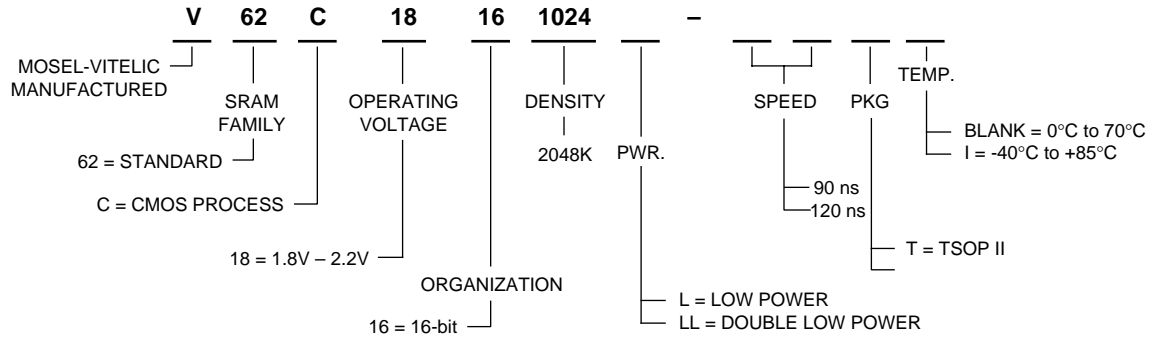**V_{CC} Power Supply**

GND   Ground

Pin Configurations (Top View)

44-Pin TSOP-II

Left Pin	#		#	Right Pin
A4	1 ●		44	A5
A3	2		43	A6
A2	3		42	A7
A1	4		41	$\overline{OE}$
A0	5		40	$\overline{UBE}$
$\overline{CE}$	6		39	$\overline{LBE}$
I/O0	7		38	I/O15
I/O1	8		37	I/O14
I/O2	9		36	I/O13
I/O3	10		35	I/O12
VCC	11		34	GND
GND	12		33	VCC
I/O4	13		32	I/O11
I/O5	14		31	I/O10
I/O6	15		30	I/O9
I/O7	16		29	I/O8
$\overline{WE}$	17		28	CE2/NC*
A15	18		27	A8
A14	19		26	A9
A13	20		25	A10
A12	21		24	A11
A16	22		23	NC

18161024-02

Part Number Information

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        V   62   C   18   16  1024        –
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MOSEL-VITELIC MANUFACTURED	
62 = STANDARD	SRAM FAMILY
C = CMOS PROCESS	OPERATING VOLTAGE
18 = 1.8V – 2.2V	DENSITY 2048K — PWR.
16 = 16-bit — ORGANIZATION	SPEED — PKG — TEMP.

BLANK = 0°C to 70°C
I = -40°C to +85°C

90 ns
120 ns

T = TSOP II

L = LOW POWER
LL = DOUBLE LOW POWER

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Absolute Maximum Ratings [1]

Symbol	Parameter	Commercial	Industrial	Units
V_{CC}	Supply Voltage	-0.5 to V_{CC} + 0.5	-0.5 to V_{CC} + 0.5	V
V_N	Input Voltage	-0.5 to V_{CC} + 0.5	-0.5 to V_{CC} + 0.5	V
V_{DQ}	Input/Output Voltage Applied	V_{CC} + 0.3	V_{CC} + 0.3	V
T_{BIAS}	Temperature Under Bias	-10 to +125	-65 to +135	°C
T_{STG}	Storage Temperature	-55 to +125	-65 to +150	°C

NOTE:
1. Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

Capacitance* T_A = 25°C, f = 1.0MHz

Symbol	Parameter	Conditions	Max.	Unit
C_{IN}	Input Capacitance	V_{IN} = 0V	6	pF
C_{OUT}	Output Capacitance	$V_{I/O}$ = 0V	8	pF

NOTE:
1. This parameter is guaranteed and not tested.

Truth Table

Mode	$\overline{CE}$	$\overline{OE}$	$\overline{WE}$	$\overline{UBE}$	$\overline{LBE}$	I/O_{8-15} Operation	I/O_{0-7} Operation
Standby	H	X	X	X	X	High Z	High Z
Output Disable	L	X	X	H	H	High Z	High Z
Output Disable	L	H	H	X	X	High Z	High Z
Read	L	L	H	L	L	D_{OUT}	D_{OUT}
Read	L	L	H	L	H	D_{OUT}	High Z
Read	L	L	H	H	L	High Z	D_{OUT}
Write	L	X	L	L	L	D_{IN}	D_{IN}
Write	L	X	L	L	H	D_{IN}	High Z
Write	L	X	L	H	L	High Z	D_{IN}

NOTE:
X = Don't Care, L = LOW, H = HIGH

DC Electrical Characteristics (over all temperature ranges, V_{CC} = 1.8V – 2.2V)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V_{IL}	Input LOW Voltage[1,2]		-0.3	—	0.4	V
V_{IH}	Input HIGH Voltage[1]		1.6	—	V_{CC} + 0.2	V
I_{IL}	Input Leakage Current	V_{CC} = Max, V_{IN} = 0V to V_{CC}	-1	—	1	μA
I_{OL}	Output Leakage Current	V_{CC} = Max, $\overline{CE}$ = V_{IH}, V_{OUT} = 0V to V_{CC}	-1	—	1	μA
V_{OL}	Output LOW Voltage	V_{CC} = Min, I_{OL} = 2.1mA	—	—	0.4	V
V_{OH}	Output HIGH Voltage	V_{CC} = Min, I_{OH} = -1mA	1.6	—	—	V

| Symbol	Parameter	Power	Com.[4]	Ind.	Units
I_{CC}	Operating Power Supply Current, $\overline{CE}$ = V_{IL}, Output Open, V_{CC} = Max., f = 0	L	4	5	mA
		LL	3	4	
I_{CC1}	Average Operating Current, $\overline{CE}_1$ = V_{IL}, Output Open, V_{CC} = Max., f = f_{MAX}[3]		20	30	mA
I_{SB}	TTL Standby Current $\overline{CE} \geq V_{IH}$, V_{CC} = Max., f = f_{MAX}[3]	L	0.5	0.7	mA
		LL	0.4	0.7	
I_{SB1}	CMOS Standby Current, $\overline{CE} \geq V_{CC} - 0.2V$, $V_{IN} \geq V_{CC} - 0.2V$ or $V_{IN} \leq 0.2V$, V_{CC} = Max., f = 0	L	5	8	μA
		LL	1	2	

NOTES:
1. These are absolute values with respect to device ground and all overshoots due to system or tester noise are included.
2. V_{IL} (Min.) = -3.0V for pulse width < 20ns.
3. f_{MAX} = 1/t_{RC}.
4. Maximum values.

AC Test Conditions

Input Pulse Levels	0 to 1.6V
Input Rise and Fall Times	5 ns
Timing Reference Levels	1.0V
Output Load	see below

AC Test Loads and Waveforms
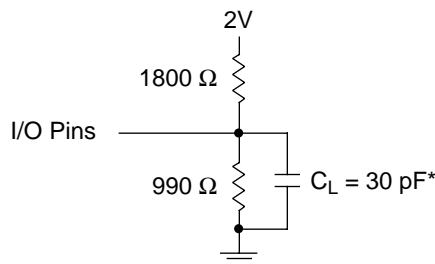
* Includes scope and jig capacitance

18161024-04

Key to Switching Waveforms

| WAVEFORM	INPUTS	OUTPUTS
	MUST BE STEADY	WILL BE STEADY
	MAY CHANGE FROM H TO L	WILL BE CHANGING FROM H TO L
	MAY CHANGE FROM L TO H	WILL BE CHANGING FROM L TO H
	DON'T CARE: ANY CHANGE PERMITTED	CHANGING: STATE UNKNOWN
	DOES NOT APPLY	CENTER LINE IS HIGH IMPEDANCE "OFF" STATE

Data Retention Characteristics

Symbol	Parameter		Power		Min.	Typ.[2]	Max.	Units
V_{DR}	V_{CC} for Data Retention $\overline{CE} \geq V_{CC} - 0.2V$, $V_{IN} \geq V_{CC} - 0.2V$, or $V_{IN} \leq 0.2V$				2.0	—	3.6	V
I_{CCDR}	Data Retention Current $\overline{CE} \geq V_{DR} - 0.2V$, $V_{IN} \geq V_{CC} - 0.2V$, or $V_{IN} \leq 0.2V$		Com'l	L	—	1	3	μA
				LL	—	0.5	1	
			Ind.	L	—	—	5	
				LL	—	—	3	
t_{CDR}	Chip Deselect to Data Retention Time				0	—	—	ns
t_R	Operation Recovery Time (see Retention Waveform)				t_{RC}[1]	—	—	ns

NOTES:
1. t_{RC} = Read Cycle Time
2. T_A = +25°C.

Low V_{CC} Data Retention Waveform ($\overline{CE}$ Controlled)

18161024-05
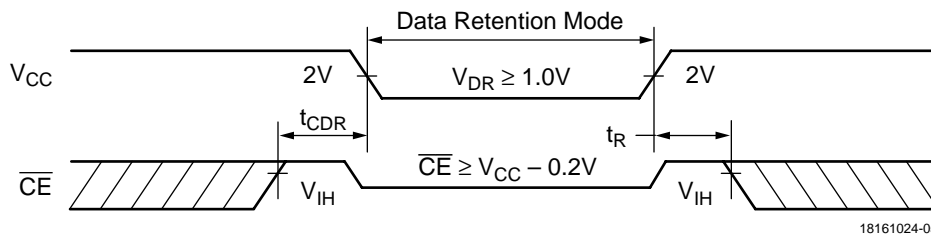
AC Electrical Characteristics

(over all temperature ranges)

Read Cycle

Parameter Name	Parameter	90		120		Unit
		Min.	Max.	Min.	Max.	
t_{RC}	Read Cycle Time	90	—	120	—	ns
t_{AA}	Address Access Time	—	90	—	120	ns
t_{ACS}	Chip Enable Access Time	—	90	—	120	ns
t_{BA}	$\overline{UBE}$, $\overline{LBE}$ Access Time	—	40	—	50	ns
t_{OE}	Output Enable to Output Valid	—	40	—	50	ns
t_{CLZ}	Chip Enable to Output in Low Z	10	—	10	—	ns
t_{BLZ}	$\overline{UBE}$, $\overline{LBE}$ to Output in Low Z	10	—	10	—	ns
t_{OLZ}	Output Enable to Output in Low Z	10	—	10	—	ns
t_{CHZ}	Chip Disable to Output in High Z	0	35	0	40	ns
t_{OHZ}	Output Disable to Output in High Z	0	30	0	35	ns
t_{BHZ}	$\overline{UBE}$, $\overline{LBE}$ to Output in High Z	0	30	0	35	ns
t_{OH}	Output Hold from Address Change	10	—	10	—	ns

Write Cycle

Parameter Name	Parameter	90		120		Unit
		Min.	Max.	Min.	Max.	
t_{WC}	Write Cycle Time	90	—	120	—	ns
t_{CW}	Chip Enable to End of Write	75	—	100	—	ns
t_{AS}	Address Setup Time	0	—	0	—	ns
t_{AW}	Address Valid to End of Write	75	—	75	—	ns
t_{WP}	Write Pulse Width	65	—	95	—	ns
t_{WR}	Write Recovery Time	0	—	0	—	ns
t_{WHZ}	Write to Output High-Z	0	35	0	40	ns
t_{WLZ}	Write to Output Low Z	10	—	15	—	ns
t_{DW}	Data Setup to End of Write	35	—	40	—	ns
t_{DH}	Data Hold from End of Write	0	—	0	—	ns
t_{BW}	$\overline{UBE}$, $\overline{LBE}$ to End of Write	70	—	80	—	ns

Switching Waveforms (Read Cycle)

Read Cycle 1[1, 2]

ADDRESS

t_{RC}

t_{AA}

$\overline{OE}$

t_{OE}

t_{OHZ}[5]

t_{OLZ}

t_{BLZ}

t_{BHZ}

$\overline{UBE}, \overline{LBE}$

t_{BA}

I/O
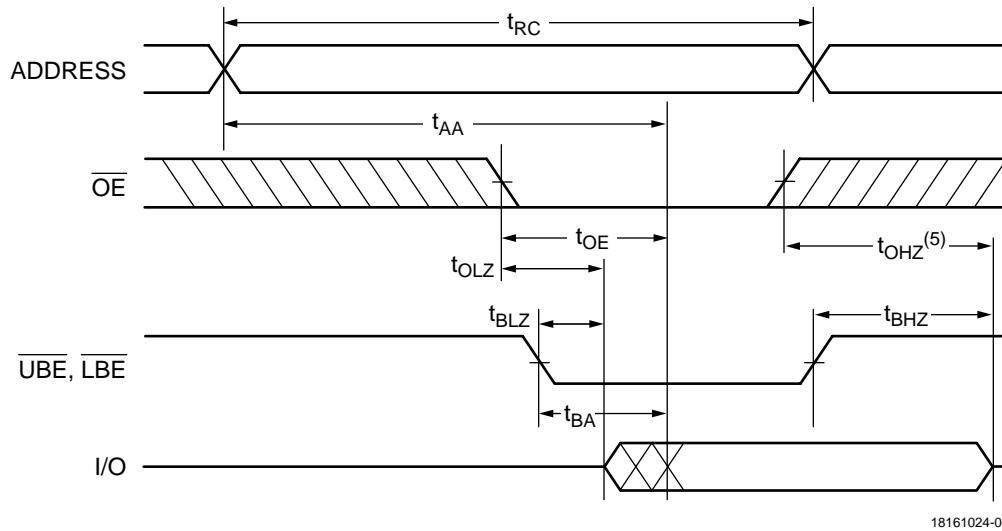
18161024-06

Read Cycle 2[1, 2, 4, 6]

ADDRESS

t_{RC}

t_{OH}

t_{AA}

t_{OH}

I/O
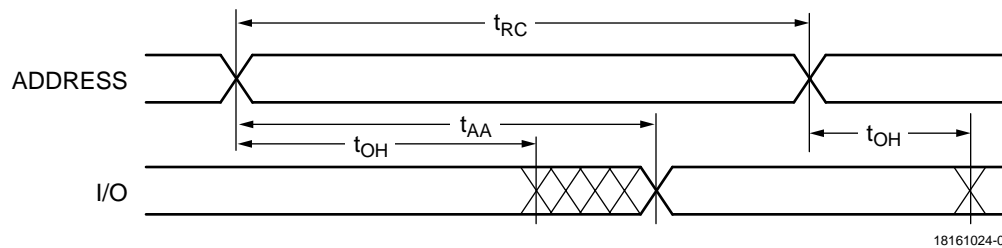
18161024-07

Read Cycle 3[1, 3, 4, 6]

ADDRESS

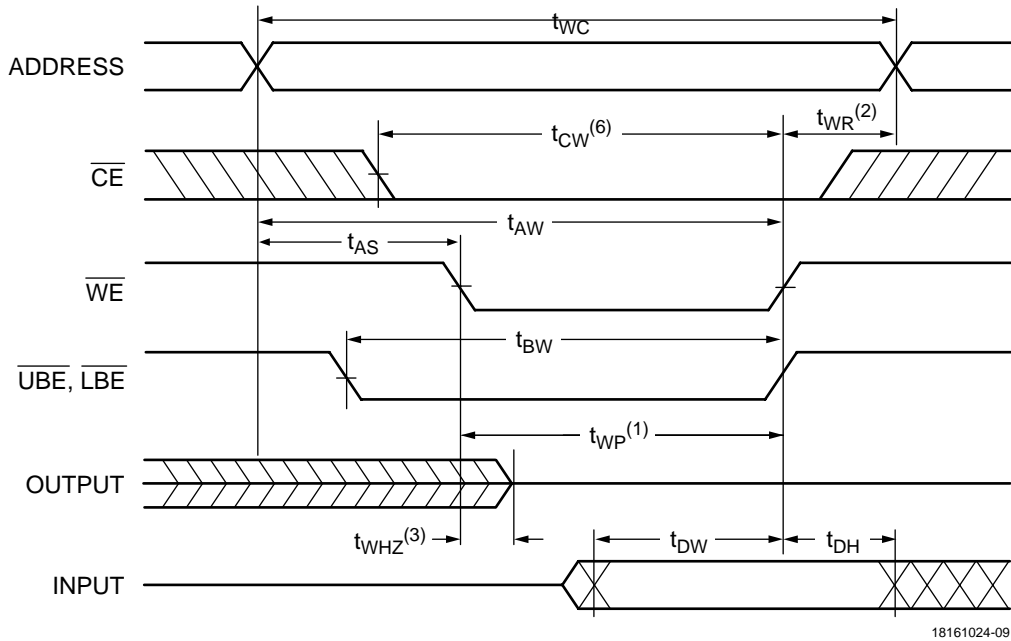t_{ACS}

$\overline{CE}$

t_{CLZ}[5]

t_{CHZ}[5]

I/O
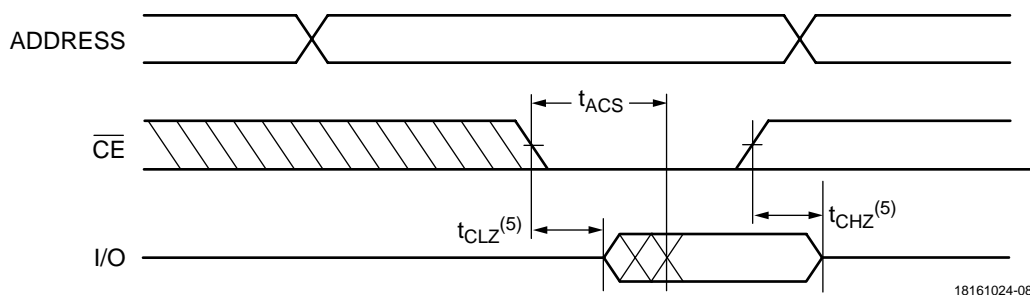
18161024-08

NOTES:
1. $\overline{WE} = V_{IH}$.
2. $\overline{CE}_1 = V_{IL}$.
3. Address valid prior to or coincident with $\overline{CE}$ transition LOW.
4. $\overline{OE} = V_{IL}$.
5. Transition is measured ±500mV from steady state with $C_L = 5pF$. This parameter is guaranteed and not 100% tested.
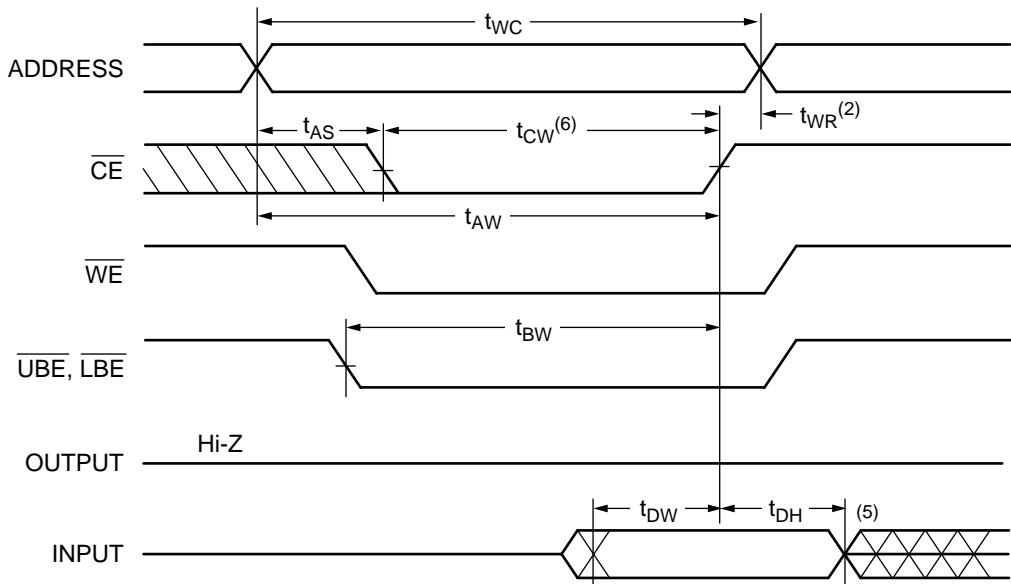6. $\overline{UBE} = V_{IL}$, $\overline{LBE} = V_{IL}$.

Switching Waveforms (Write Cycle)

Write Cycle 1 ($\overline{WE}$ Controlled)[4]

18161024-09

Write Cycle 2 ($\overline{CE}$ Controlled)[4]
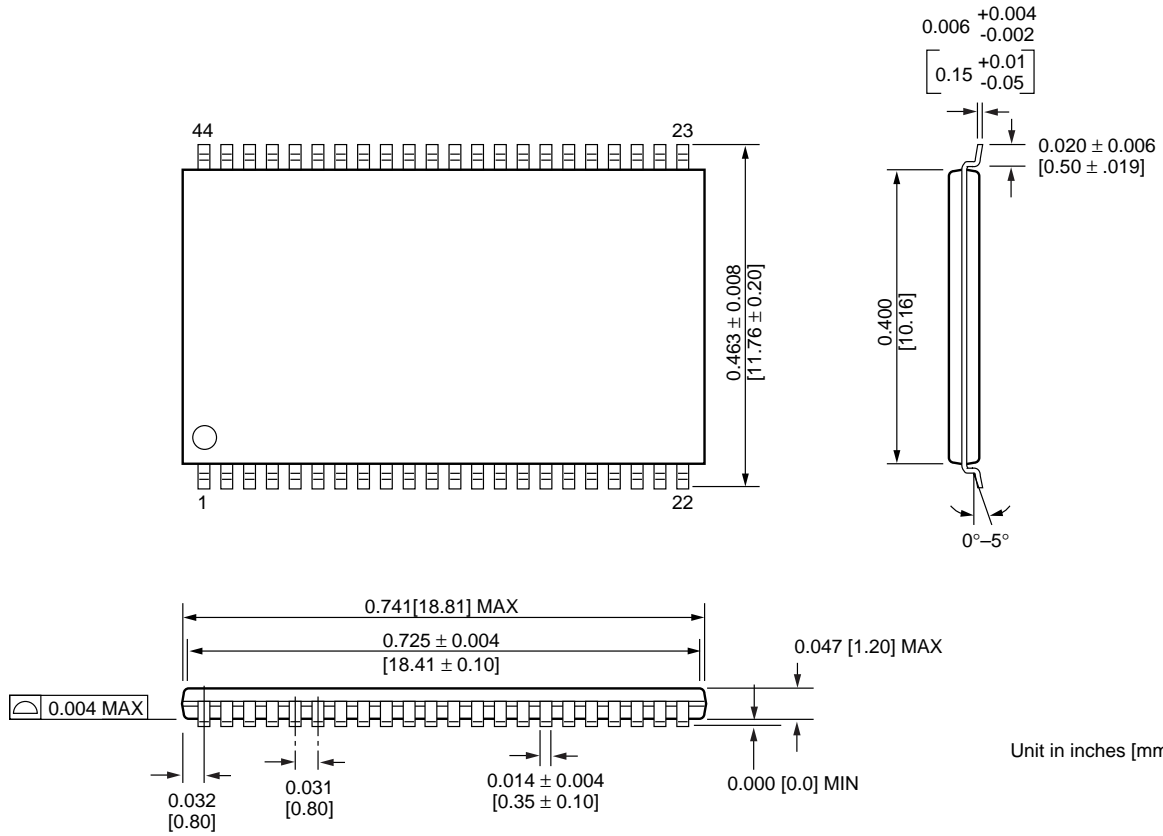

18161024-10

NOTES:

1. The internal write time of the memory is defined by the overlap of $\overline{CE}$ active and $\overline{WE}$ low. All signals must be active to initiate and any one signal can terminate a write by going inactive. The data input setup and hold timing should be referenced to the second transition edge of the signal that terminates the write.
2. t_{WR} is measured from the earlier of $\overline{CE}$ or $\overline{WE}$ going high.
3. During this period, I/O pins are in the output state so that the input signals of opposite phase to the outputs must not be applied.
4. $\overline{OE} = V_{IL}$ or V_{IH}. However it is recommended to keep $\overline{OE}$ at V_{IH} during write cycle to avoid bus contention.
5. If $\overline{CE}$ is LOW during this period, I/O pins are in the output state. Then the data input signals of opposite phase to the outputs must not be applied to them.
6. t_{CW} is measured from $\overline{CE}$ going low to the end of write.

Package Diagrams

44-pin 400 mil TSOP-II

44   23

1   22

0.463 ± 0.008
[11.76 ± 0.20]

0.006 $^{+0.004}_{-0.002}$

0.15 $^{+0.01}_{-0.05}$

0.020 ± 0.006
[0.50 ± .019]

0.400
[10.16]

0°–5°

0.741[18.81] MAX

0.725 ± 0.004
[18.41 ± 0.10]

0.047 [1.20] MAX

0.004 MAX

0.032
[0.80]

0.031
[0.80]

0.014 ± 0.004
[0.35 ± 0.10]

0.000 [0.0] MIN

Unit in inches [mm]

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